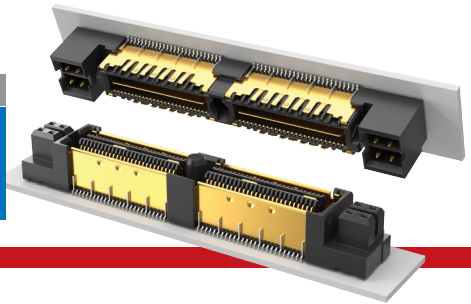




(0.635 mm) .025" PITCH • QMSS/QFSS SERIES

NRZ

14
Gbps



QMSS
Board Mates:
QFSS

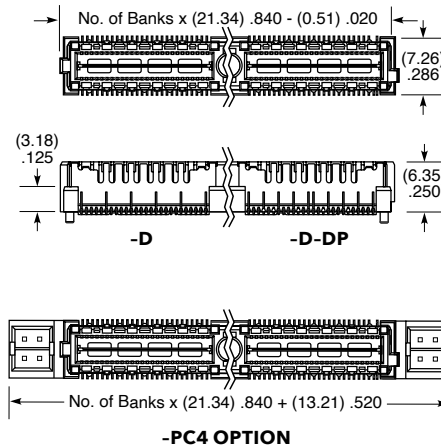
QFSS
Board Mates:
QMSS

QMSS/QFSS
Standoffs:
SO

SPECIFICATIONS

Insulator Material:
Liquid Crystal Polymer
Terminal, Ground Plane & Shield Material:
Phosphor Bronze
Plating:
Au over 50 μ " (1.27 μ m) Ni
(Tin on Ground Plane Tail)
Operating Temp Range:
-55 °C to +125 °C
Current Rating:
Contact:
3.4 per pin (4 adjacent pins powered)
Ground Plane:
7.8 A per ground plane
(2 ground planes powered)
Voltage Rating:
300 VAC/424 VDC

QMSS	PINS PER ROW NO. OF PAIRS	06.75	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank / 40 signals + 12 grounds to shield = -D)		-L = 10 μ " (0.25 μ m) Gold on contact, Matte Tin on tail	-D = Single- Ended		-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad (N/A with -PC4)
	-016, -032, -048 (16 pairs per bank = -D-DP)			-D-DP = Differential Pair		-PC4 = 4 Power Pins/End (N/A with -A)

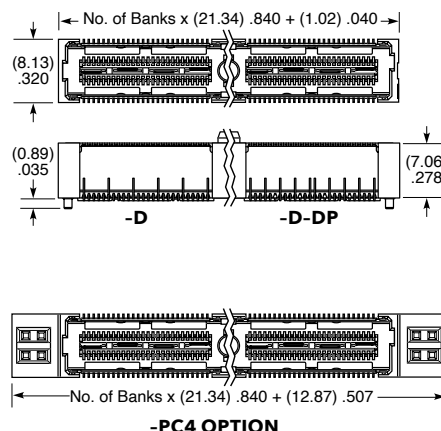


PACKAGING OPTION

Tape & Reel
Options
(-TR & -FR)
available. Visit
series web
page and view
engineering prints
for complete
specifications.

View complete specifications at: samtec.com?QMSS

QFSS	PINS PER ROW NO. OF PAIRS	04.25	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank / 40 signals + 12 grounds to shield = -D)		-L = 10 μ " (0.25 μ m) Gold on contact, Matte Tin on tail	-D = Single- Ended		-PC4 = 4 Power Pins/End (N/A with -A)
	-016, -032, -048 (16 pairs per bank = -D-DP)			-D-DP = Differential Pair		

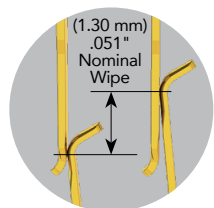


PACKAGING OPTION

Tape & Reel
Options
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for complete
specifications.

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max
(026-078)
Board Stacking:
For applications requiring
more than two connectors
contact ipg@samtec.com



Note:
Some lengths, styles and
options are non-standard,
non-returnable.

View complete specifications at: samtec.com?QFSS